TECHNICAL DATASHEET

Fast Cure PREPAG 30Min

Epoxy Coated Nomex
(For Adhesion of Conductors)
No. ECNFC 8.140

Description

ECNFC No.8.140 is manufactured using Nomex Aramid Paper, impregnated on both side with Epoxy Resin. It is a fast curing sheet with good adhesion properties. It can be used upto temp 155 Degree C for Class F Insulation.

Features

- Dry
- Good Stiffness
- Tack Free
- Excellent Adhesion
- Smooth Surface
- Quick Curing
- High Resin Content

Application

SCFT 8.140 finds its application for adhesion of copper coils of high voltage machines where Class F Insulation is required.

Properties

<table>
<thead>
<tr>
<th>Properties</th>
<th>Unit</th>
<th>Values</th>
<th>Test Method</th>
</tr>
</thead>
<tbody>
<tr>
<td>Thickness Nominal</td>
<td>mm</td>
<td>0.20+/-0.03</td>
<td>IEC 60394-2</td>
</tr>
<tr>
<td>Total Weight</td>
<td>g/sqm</td>
<td>140 +/-15</td>
<td>IEC 60394-2</td>
</tr>
<tr>
<td>Nomex</td>
<td>g/sqm</td>
<td>41+/-4</td>
<td>IEC 60394-2</td>
</tr>
<tr>
<td>Volatile Content</td>
<td>%</td>
<td>&lt;/5</td>
<td>IEC 60394-2</td>
</tr>
<tr>
<td>Adhesion Strength</td>
<td>N</td>
<td>&gt;/800</td>
<td>IEC 60394-2</td>
</tr>
</tbody>
</table>
Curing Schedule/Condition

Ecnfc No 8.140 should be cured after it is applied on the conductors in a hot press at 130 Degree C or 150 Degree C with pressing time for 15min to 30 minutes. Before opening the press it is recommended to cool down below 80 Degree C. This will give a better bonding with copper conductor.

Availability

Roll Width: From 15mm to 880mm +/-1mm

Storage

Ecnfc No.8.140 should be stored in cool, clean and dry condition always covered inside the polythene

Shelf Life

At Standard Temp of 20+/−5 Degree C : 3 Months
At Refrigerated Storage of 5 Degree C : 6 Months

DISCLAIMER

All information, recommendations and test data herein are offered only as a guide. We believe them to be accurate but do not guarantee results, freedom from patent infringement, suitability of this product for any resultant application.